

Docket No.: M4065.0239/P239

(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: Larry Hillyer, et al.

Application No.: 09/653,561

Filed: August 31, 2000

For: METHOD AND MATERIAL FOR REMOVING ETCH RESIDUE FROM HIGH ASPECT RATIO CONTACT SURFACES

4/Election P.Walton 11-28-01 Group Art Unit: 2811

Examiner: S. Clark

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents Washington, DC 20231

Dear Sir:

In response to the restriction requirement set forth in the Office Action mailed November 6, 2001, Applicants hereby provisionally elect Group I (i.e., claims 1-44 and 50-53) for continued examination, without traverse.

The claims of this application are believed to be in immediate condition for allowance. Applicants respectfully solicit an office action on the merits and, subsequently, the allowance of at least claims 1-44 and 50-53.

Dated: November 21, 2001

Respectfully submitted,

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